PRF15_102 Series

No.	Item	Rating Value	Metheod of Examination
1	Resistance Value at 25°C	Within the specified range	After applying maximum operating voltage for 3 mins. and leaving for 2 hours in 25°C, measured by applying voltage less than DC1.0V.
2	Vibration	 Appearance: No defects or abnormalities Resistance (R25) change: Less than ±20% (*) 	Reference standard: IEC 60068-2-6 (2007) · Soldered PTC to PCB (**) · Frequency range: 10 to 55Hz · Amplitude: 1.5mm · Sweep rate: 1 octave/min. · Direction: X-Y-Z (3 direction) · 24 cycles in each axis
3	Solderability	Wetting of soldering area: ≥95%	Reference standard: IEC 60068-2-58 (2004) · Solder: Sn-3.0Ag-0.5Cu · Solder temp.: 245±5°C · Immersion time: 3±0.3s
4	Resistance to Soldering Heat	 Appearance: No defects or abnormalities Resistance (R25) change: Less than ±20% (*) 	Reference standard: IEC 60068-2-58 (2004) [Solder bath method] · Solder: Sn-3.0Ag-0.5Cu · Preheat: 150±5°C, 90 to 120s · Solder temp.: 260±5°C · Immersion time: 10±1s
5	High Temperature Storage	 Appearance: No defects or abnormalities Resistance (R25) change: Less than ±20% (*) 	Reference standard: IEC 60068-2-2 (2007) · Soldered PTC to PCB (**) · (Max. operating temp.)±2°C · 1000+48/-0 hrs.
6	Low Temperature Storage		Reference standard: IEC 60068-2-1 (2007) · Soldered PTC to PCB (**) · (Min. operating temp.)±3°C · 1000+48/-0 hrs
7	Damp Heat, Steady State		Reference standard: IEC 60068-2-67 (1995) · Soldered PTC to PCB (**) · +85±2°C, 85±5%RH · 1000+48/-0 hrs
8	Thermal Shock		Reference standard: IEC 60068-2-14 (2009) [Test Na] · Soldered PTC to PCB (**) · Transport time: <10 sec. · Test condition: See below table
			Step Condition Time 1 (Min. Operating temp.)±3°C 30min. 2 (Max. Operating temp.)±2°C 30min.
9	High Temperature Load		Test cycle: 5 cycles Reference standard: IEC 60068-2-2 (2007) Soldered PTC to PCB (**) (Max. operating temp.)±2°C Applied max. voltage 1000+48/-0 hrs.

*: The resistance value after the test. It is measured by applying voltage less than DC1.0V after left at 25±2°C for 2hrs.
 **: Above mentioned soldering is done under the following conditions at our side.
 • Glass-Epoxy PC board
 • Standard land dimension

· Standard solder paste

· Standard solder profile

Above conditions are mentioned in Notice.

